

SPECIFICATION AMENDMENTS:

Please amend the specification as follows:

Please replace the current paragraph at page 20, line 17, through page 21, line 1, with the following amended paragraph:

A sealing layer 30 formed from an epoxy resin or the like is formed on the upper side of the first semiconductor chip 5 such that the top face (i.e. the end face) 26a of the post portions 26 and an upper face 17a of the glass plate 17 are exposed. More specifically, the sealing layer 30 is provided on the insulation film 18, on the wiring layer 24, and on side surfaces of the post portions 26, and surrounds a side surface of the glass plate 17, as shown in Fig. 2(B). The sealing layer 30 may be formed to be in direct contact with the side surface of the glass plate 17, as shown in Fig. 2(B). The solder balls 28 serving as external terminals for connecting the image-capturing semiconductor device 10 to the second printed circuit board 53 are formed on the top face of each post portion 26. Note that in this constitutional example, the upper face 17a of the glass plate 17 indicates the surface of the glass plate 17 which opposes the exposed face of the sensor portion 14, or in other words the surface of the glass plate on the opposite side to a rear face 17b of the glass plate.